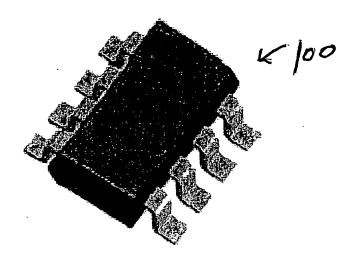
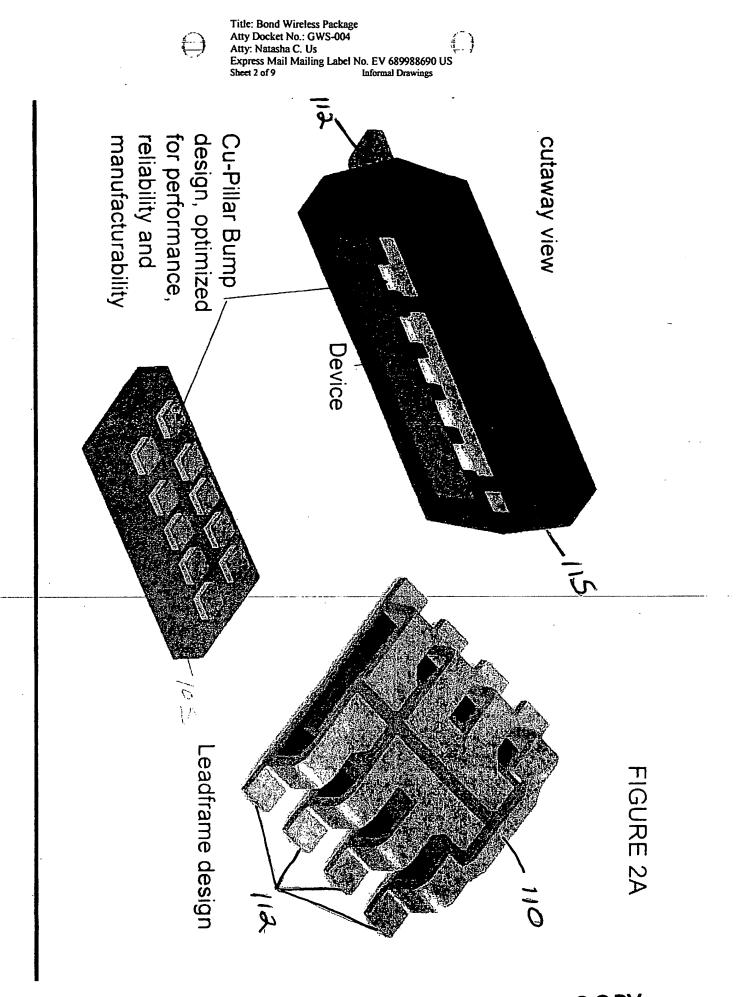
Title: Bond Wireless Package Atty Docket No.: GWS-004

Atty: Natasha C. Us
Express Mail Mailing Label No. EV 689988690 US Informal Drawings



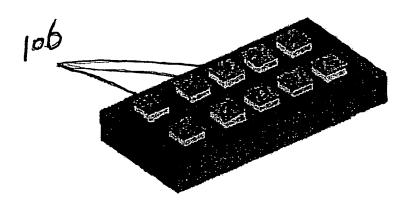
## FIGURE 1



DEST AVAILABLE COPY







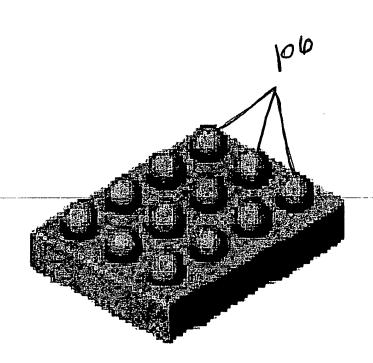
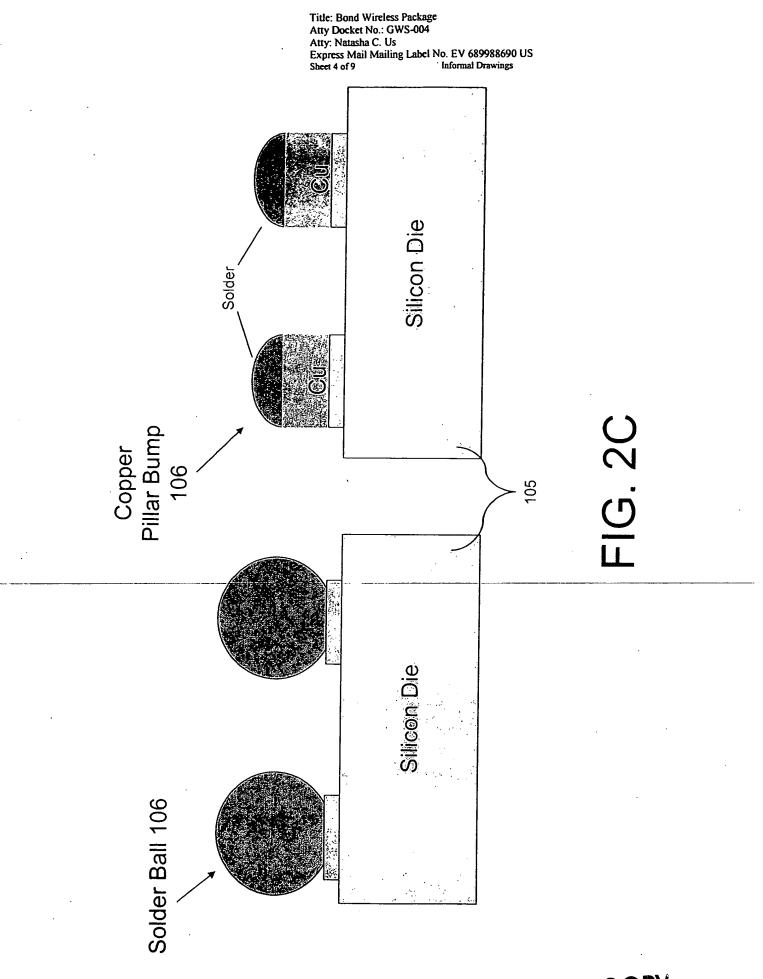


FIGURE 2B



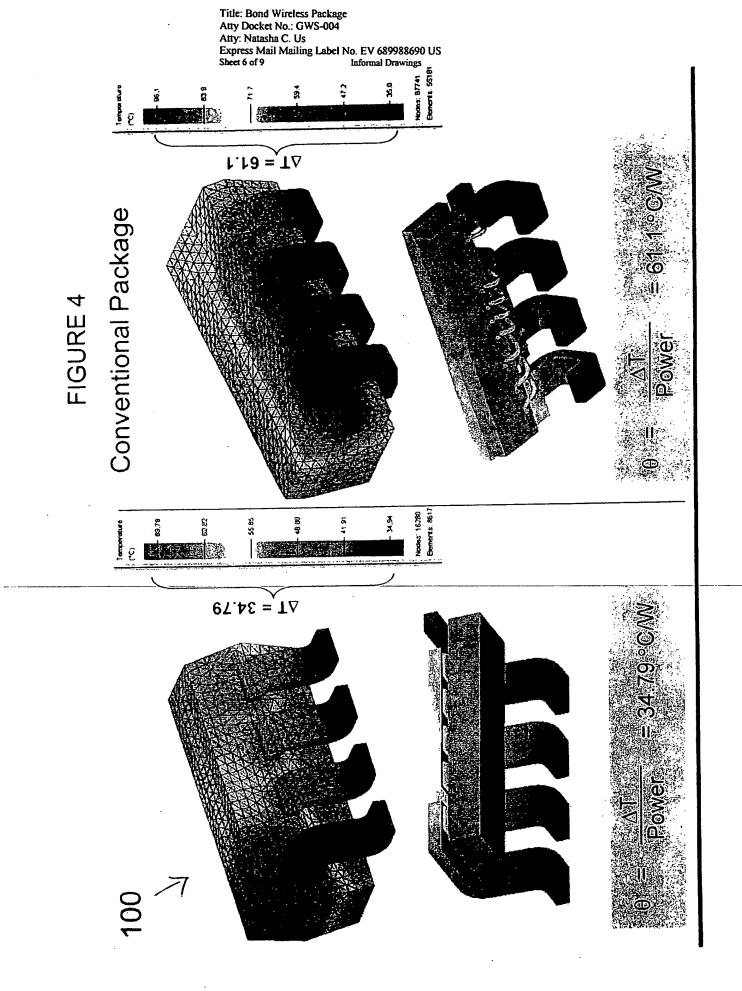
BEST AVAILABLE COPY

Title: Bond Wireless Package Atty Docket No.: GWS-004 Atty: Natasha C. Us Express Mail Mailing Label No. EV 689988690 US Sheet 5 of 9 Informal Drawings FIGURE 3

COMMON

S

**BEST AVAILABLE COPY** 



Title: Bond Wireless Package Atty Docket No.: GWS-004 Atty: Natasha C. Us

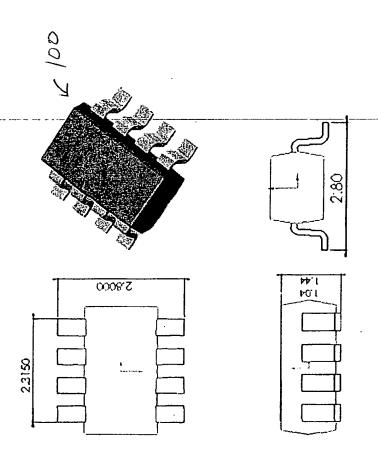
Express Mail Mailing Label No. EV 689988690 US

Sheet 7 of 9

Informal Drawings

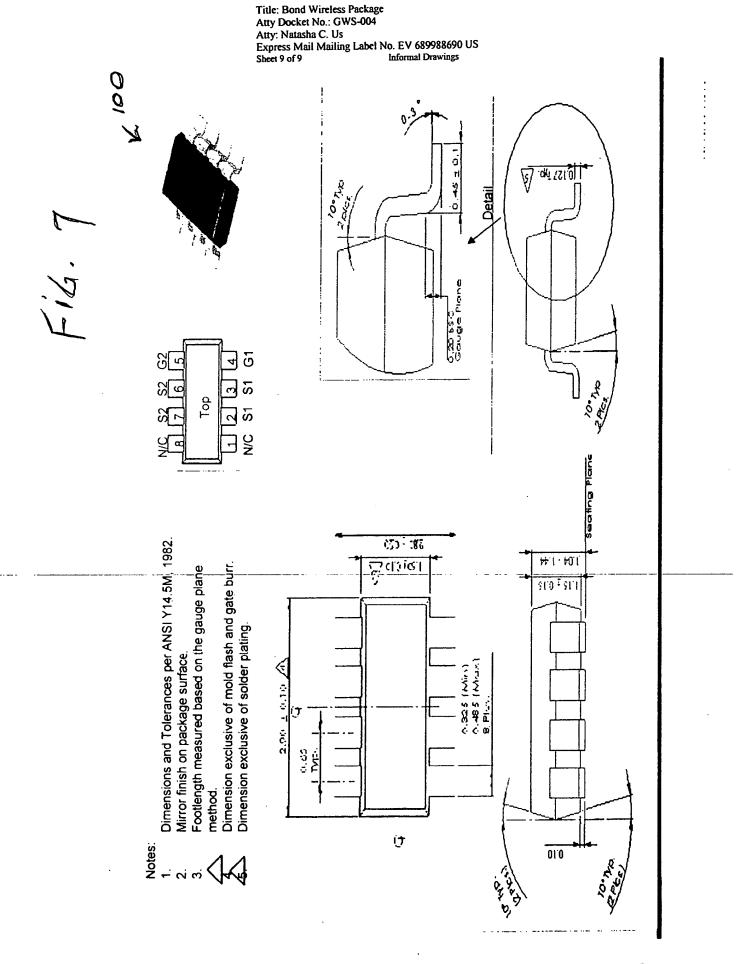
CONVENTIONAL PACKAGE INVENTION 10  2.35E+08  1.06E+08  2.35E+08  2.35E+08  2.35E+08  3.1 uM  3.1 uM  3.1 uM  4.0 uM  4.0 uM  2.29E+08  2.29E+08  2.29E+08  3.229E+08  3.23E+07  3.3 uM  3.4 uM  3.5 uM  3.5 uM  3.6 uM  3.7 uM  3.7 uM  3.7 uM				
lars  lars  Lose + 08  2.35E + 08  1.06E + 08  2.35E + 08  2.35E + 08  6.51E + 07  Ement 3.1 uM  2.48E + 08  2.99E + 08  2.99E + 08  3.24E + 08  2.29E + 08  2.29E + 08  2.29E + 08  2.29E + 08  3.7 uM  3.7 uM  3.7 uM  3.7 uM  3.1 uM  3.3 uM  3.4 uM  4.0 uM  3.5 2.29E + 08  3.5 2.29E + 08  3.7 uM  3.7 uM  3.7 uM  3.7 uM		CONVEN	TIONAL PACKAGE	INVENTION 100
lars  Lind  2.35E+08  1.06E+08  2.35E+08  2.35E+08  3.1 uM  2.48E+08  2.99E+08  2.99E+08  2.48E+08  3.1 uM  2.29E+08  3.2 uM  4.0 uM  2.29E+08  3.2 uM  3.3 uM  3.3 uM  3.4 und  3.2 29E+08  3.3 uM  3.4 und  3.4 und  3.5 uM  4.0 uM  3.7 uM  3.4 und  3.5 uM  4.0 und  3.7 uM  3.7 uM			The Manager	三 一
und 2.35E+08 1.06E+08 2.35E+08 2.35E+08 6.51E+07 ement 3.1 uM 2.48E+08 1.06E+08 2.48E+08 1.06E+08 2.48E+08 2.48E+08 2.48E+08 2.48E+08 2.48E+08 2.29E+08 2.29E+08 3.7 uM 3.7 uM 3.7 uM 3.7 uM 3.7 uM 3.7 uM				
lars  1.06E+08 2.35E+08 2.35E+08 6.51E+07 ement 3.1 uM 2.99E+08 2.48E+08 14ss 2.48E+08 9.32E+07 ement 4.0 uM 2.29E+08 2.29E+08 3.7 uM	Mold Compound		2.35E+08	7.16E+07
lars  2.35E+08 64 64 65.1E+07 6ment 3.1 uM 65.1E+07 65.1E+08 2.99E+08 2.99E+08 6.32E+07 6ment 4.0 uM 62.29E+08 2.29E+08 6.55E+08	Leadframe		1.06E+08	8.14E+07
lars  care	Die		2.35E+08	5.73E+07
ement 3.1 uM 3.1 uM 3.1 uM 2.99E+08 2.99E+08 2.48E+08 2.48E+08 3.2 L48E+08 3.3 L4M 3.3 L4M	Solder on Pillars		The second secon	6.21E+07
ids 2.35E+08 6.51E+07  ement 3.1 uM 2.48E+08 2.99E+08 2.48E+08 3.248E+08 9.32E+07  ement 4.0 uM 2.29E+08 2.29E+08 3.7 uM 3.7 uM 3.7 uM 3.7 uM	Cu Pillars	(2). (3).		9.90E+07
6.51E+07  ement 3.1 uM  2.48E+08  2.99E+08  2.48E+08  lars  2.48E+08  9.32E+07  ement 4.0 uM  2.29E+08  2.29E+08  3.7 uM  3.7 uM  3.7 uM	Gold wirebonds		2.35E+08	理 海南京 二十二十二十二十二十二十二十二十二十二十二十二十二十二十二十二十二十二十二十
and 2.48E+08  und 2.48E+08 2.99E+08 2.48E+08 4.0 uM  ement 4.0 uM 2.29E+08 2.29E+08 2.29E+08 3.7 uM 3.7 uM 3.7 uM	Die attach		6.51E+07	
lars  Land  2.48E+08  2.99E+08  2.48E+08  2.48E+08  9.32E+07  ement  4.0 uM  2.29E+08  2.29E+08  2.29E+08  3.7 uM  3.7 uM	Max Displacement		3.1 uM	1.93 uM
und 2.48E+08 2.99E+08 2.48E+08 3.248E+08 9.32E+07 ement 4.0 uM 2.29E+08 2.29E+08 2.29E+08 3.7 uM 3.7 uM	是一个一个一个一个一个一个一个一个一个一个一个一个一个一个一个一个一个一个一个		「	
2.99E+08 2.48E+08 2.48E+08 9.32E+07 4.0 uM 2.29E+08 2.29E+08 2.29E+08 3.7 uM 3.7 uM	Mold Compound		2.48E+08	1.28E+08
2.48E+08 2.48E+08 9.32E+07 4.0 uM 4.0 uM 2.29E+08 2.76E+08 2.29E+08 2.29E+08 8.60E+07 3.7 uM	Leadframe		2.99E+08	3.28E+08
2.48E+08 9.32E+07 4.0 uM 2.29E+08 2.76E+08 2.29E+08 2.29E+08 8.60E+07 3.7 uM	Die		2,48E+08	1.08E+08
2.48E+08 9.32E+07 4.0 uM 2.29E+08 2.29E+08 2.29E+08 3.7 uM	Solder on Pillars			1.14E+08
2.48E+08 9.32E+07 4.0 uM 2.29E+08 2.29E+08 2.29E+08 3.29E+08 3.7 uM	Cu Pillars			1.78€+08
9.32E+07 4.0 uM 2.29E+08 2.76E+08 2.29E+08 2.29E+08 8.60E+07	Gold wirebonds		2.48E+08	
2.29E+08 2.29E+08 2.29E+08 2.29E+08 8.60E+07	Die attach		9.32E+07	
2.29E+08 2.29E+08 2.29E+08 2.29E+08 8.60E+07 3.7 uM	Max Displacement		4.0 uM	5,3 uM
2.29E+08 2.76E+08 2.29E+08 2.29E+08 8.60E+07 3.7 uM				一、 一
Pillars 2.29E+08 2.29E+08 2.29E+08 3.7 uM	Mold Compound		2.29E+08	1.18E+08
Pillars 2.29E+08 Sonds 2.29E+08 8.60E+07 Recement 3.7 uM	Leadframe		2.76E+08	3.02E+08
Pillars  bonds 2.29E+08  8.60E+07  acement 3.7 uM	Die		2.29E+08	9.99E+07
3 7 uM	Solder on Pillars			1.06E+08
2.29E+08 8.60E+07 3.7 uM	Cu Pillars		•	1.63E+08
8.60E+07 3.7 uM	Gold wirebands		2.29E+08	
3.7 uM	Die attach		8.60E+07	
	Max Displacement		3.7 uM	4.9 uM

Title: Bond Wireless Package
Atty Docket No.: GWS-004
Atty: Natasha C. Us
Express Mail Mailing Label No. EV 689988690 US
Sheet 8 of 9 Informal Drawings





BEST AVAILABLE COPY



(j)

BEST AVAILABLE COPY ...